8 3 610-90681-01 REVISIONS NOTES: UNLESS OTHERWISE SPECIFIED ECO NO. REV DATE DESCRIPTION CHECKED APPROVED DRAWN SPECIFICATIONS/TOLERANCES:

 A. FABRICATE PER IPC-6012, CLASS 2, USING PROVIDED DATA FILES

 CLEU77 1.0 08/09/19 INITIAL RELEASE LIKZ CLEU CLEU A. FABRICATE PER IPC-8012, CLASS 2, USING MOVIDED UNIT FLES B. ALL SPECIFICATIONS USED SHALL BE PER THEIR LATEST REVISIONS. C. THE DIMENSIONS OF CIRCUIT FEATURES IN THE PROVIDED DATA MAY BE ADJUSTED ONLY TO COMPENSATE FOR PROCESS TOLERANCES, ADDING, REMOVING OR RELOCATING CIRCUIT FEATURES, INCLUDING MON-PUNCTIONAL PADS, IS NOT ALLOMED, AND THE MILI88 3.0 07/13/20 DESIGN UPDATE ISJP MILI MILI DESIGN OF ALL PLANE STRUCTURES MUST BE MAINTAINED TO ENSURE PROPER ELECTRICAL PERFORMANCE.

D. REMOVE ALL BURRS AND BREAK SHAPP EDGES, .381 [.015] MAX RADIUS. E. PARENTHETICAL INFORMATION IS FOR REFERENCE ONLY.
F. REPAIR OF PCB DEFECTS IS NOT PERMITTED. D 2 DIELECTRIC MATERIAL: VOIELECHTIC MATERIAL:
A. DIELECTRIC MATERIAL:
(RehS COMPLIANT EPOXY-GLASS).
B. MINIMUM DIELECTRIC THICKNESS SHALL BE .051 [.002] FOR REFERENCED STACK-UP DIMENSIONS OF .076 (.003) ON GREATER; IPC-6012 REQUIREMENTS SHALL OTHERWISE APPLY, SINGLE-PLY CONSTRUCTION IS ALLOWED.

C. SEE LAYER STACK-UP FOR REQUIRED COPPER WEIGHTS AND THE FINISHED PCB THICKNESS. IF SPECIFIED, 1/3 02. STARTING FOIL MAY BE ACHIEVED BY 1/2 02. FOIL REDUCTION.
D. FINISHED PCB THICKNESS SHALL BE MEASURED OVER LANDS AND/OR CONDUCTORS NOT COVERED BY SOLDER MASK. SE TRACE WIDTH DIFF DIFF
REF CPW IMP TRACE REF CPW
LAYER SPACE OHMS WIDTH/SPACE LAYER SPACE LAYER DESCRIPTION OHMS A. VIA DIAMETERS (TOL. = .051/- DRILL DIAMETER [*.0020/- DRILL DIAMETER])
SHALL BE VERIFIED BEFORE PLATING, ALL OTHER HOLE DIAMETERS SHALL BE LO1 - TOP .0125 0.5 OZ 50 2 VERIFIED AT FINAL INSPECTION.

B. LAYER-TO-LAYER MISREGISTRATION SHALL BE .127 [.005] MAXIMUM. LO2 - PLANE 0.5 OZ C. FILL ALL VIAS ON PASTE WITH COPPER PLATING OR NON-CONDUCTIVE EPOXY, DIMPLE DEPTH IN BGA PADS SHALL BE .025 [.001] MAXIMUM. FOR EPOXY FILL, OVERPLATE WITH COPPER .005 [.002] MINIMUM AND THE PRESENCE OF WRAP PLATING SHALL BE VISUALLY EVIDENT IN ALL DUALITY .0310 +/- 10% IO3 - PLANE 0 5 07 -- ----CONFORMANCE MICROSECTIONS; NO MINIMUM MEASUREMENT REQUIRED. A. APPLY PI SOLDER MASK USING PROVIDED DATA.

B. SOLDER MASK SHALL BE PER IPC-SM-840, CLASS T, COLOR RED.
C. THE DIMENSIONS OF SOLDER MASK-DEFINED PADS ON PLANES AND/OR WIDE LO4 - BOTTOM 0.5 OZ -- .---- --- ---- .---/.----CONDUCTORS SHALL NOT BE MODIFIED. MANALING:
A. MARK PCB PER PROVIDED DATA USING SILKSCREEN OR AUTOMATED INJET
PROCESSING WITH PERMANENT, NON-CONDUCTIVE INK, COLOR WHITE.
B. SUPPLIER ID AND TRACEABILITY INFORMATION SHALL BE APPLIED USING STACK-UP (DIMENSIONS IN INCHES) PERMANENT, NON-CONDUCTIVE INK, COLOR WHITE. C. INK SHALL NOT BE APPLIED TO ANY SOLDERABLE SURFACE. ELECTRICAL TEST:

A. DESIGN VERTICATION SHALL BE DONE PRIOR TO PCB FABRICATION USING SUPPLIED VALOR ODB. DATABASE, OR GERBER DATA AND AN IPC-D-356 NETLIST.

B. ALL PCBS SHALL BE 100% ELECTRICALLY TESTED FOR OPENS AND SHORTS USING PROVIDED DATA. USING PROVIDED DATA.

C. APPLY TEST STAMP IN NON-LEGEND AREA ON REAR SIDE OF PCB; OK TO APPLY
TO PANEL RAILS IF SPACE DOES NOT PERMIT. 7 FINAL FINISH: NAL FINISH: FINAL FINISH ON ALL EXPOSED CONDUCTORS SHALL BE 2 MICROMETER GOLD IMMERSION. B. FINAL FINISH ON ALL THE GOLD FINGER BEVEL DEFAULT VALUE:20 DEGREES,
DEPTH: 11.8MILS. FINAL FINISH ON ALL EXPOSED GOLD FINGER SHALL BE 30 MICROMETER HARD GOLD PLATED. 8. IMPEDANCE:
A. IMPEDANCE TOLERANCE SHALL BE */- 10%.
B. SEE LAYER STACK-UP FOR IMPEDANCE REQUIREMENTS. If PANELIZATION SPECIFICATIONS ARE PROVIDED, THE PCBS SHALL BE DELIVERED IN
PANEL FORM. HOWEVER, THESE SPECIFICATIONS MAY BE CHANGED AS REQUIRED BY THE
CONTRACT MANUFACTURER TO SUPPORT VOLUME ASSEMBLY REQUIREMENTS. В UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN METRIC WITH INCHES IN BRACKETS DO NOT SCALE DRAWING CIPIESS APPROVALS DATE .XXX .064 [:.005] MATERIAL .XX 1.13 [1.01] LIKZ 08/09/19 PCB FABRICATION, SEE BOM SEE BOM CLEU 08/09/19 NEXT ASSY CYW920721M2EPA1 USED ON APPLICATION 08/09/19 SIZE CAGE CODE THE INFORMATION CONTAINED HEREIN IS CONFIDENTIAL AND PROPRIETARY TO CYPRESS SEMICOMPOUTOR COMPORATION AND SHALL MOT USE REPROQUED ON MICHOGRAPH HOLD OF MICHOGRAPH HO 610-90681-01 SHEET PROJ. ENG 1 OF 2 3.0 1/1 FAB NOTES REV 08/01/14 COMPUTER GENERATED DRAWING DO NOT CHANGE MANUALLY 3 2

